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Understanding Embedded - FPGAs (Field Programmable Gate Array)

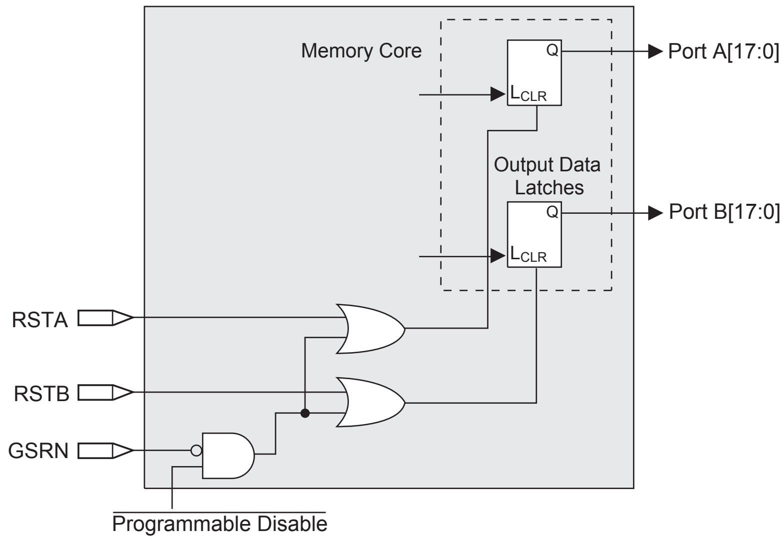
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	20000
Total RAM Bits	405504
Number of I/O	340
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp20e-5fn484c

Figure 2-15. Memory Core Reset

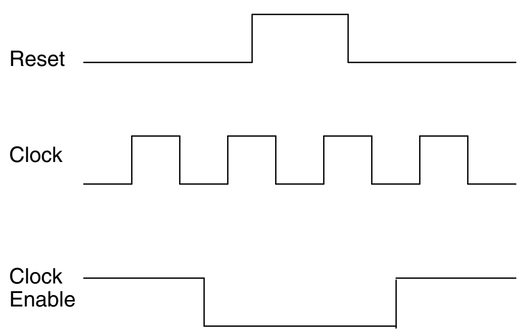


For further information on sysMEM EBR block, see the details of additional technical documentation at the end of this data sheet.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-16. The GSR input to the EBR is always asynchronous.

Figure 2-16. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

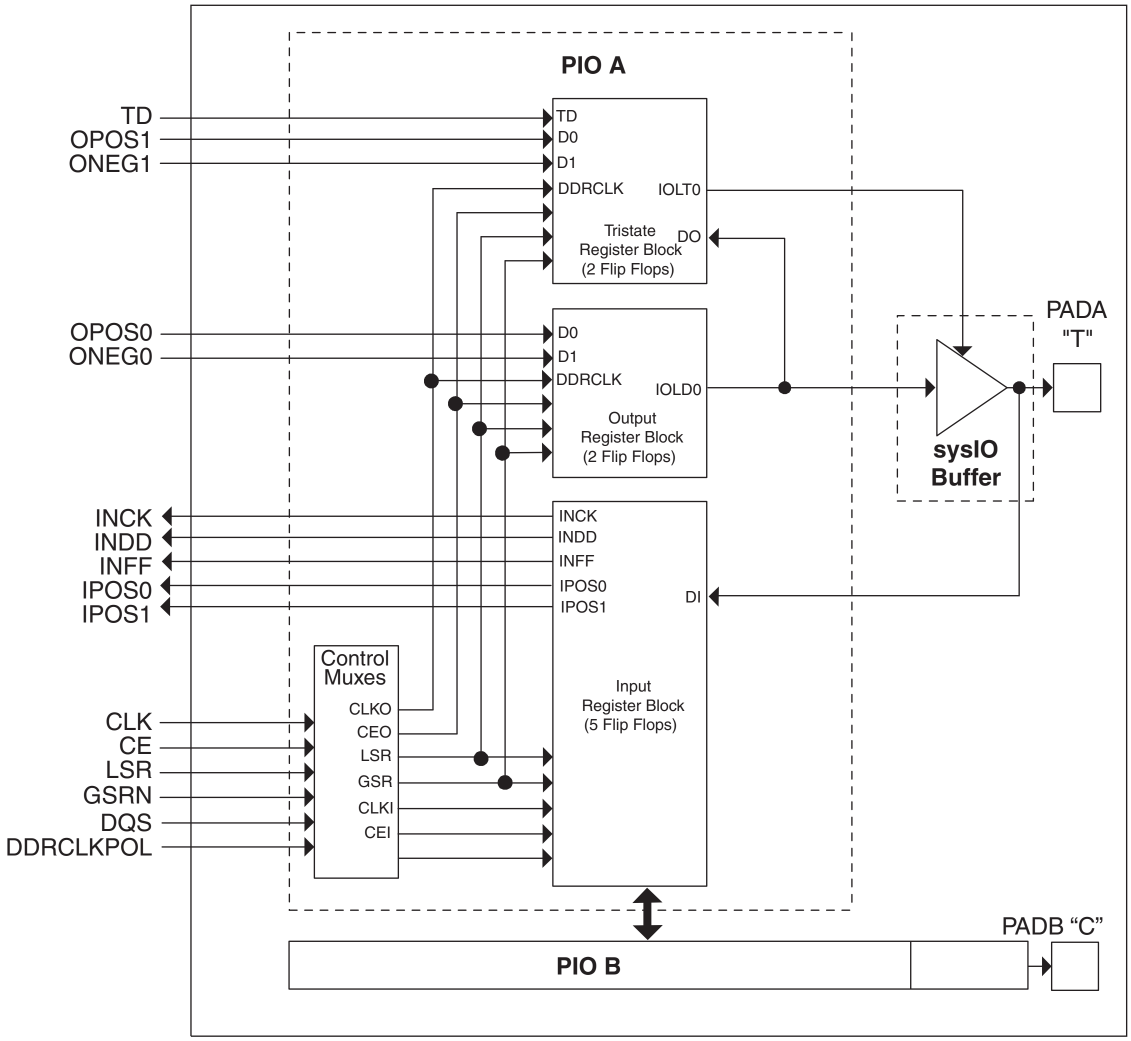
These instructions apply to all EBR RAM and ROM implementations.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

Programmable I/O Cells (PICs)

Each PIC contains two PIOs connected to their respective sysIO Buffers which are then connected to the PADs as shown in Figure 2-17. The PIO Block supplies the output data (DO) and the Tri-state control signal (TO) to sysIO buffer, and receives input from the buffer.

Figure 2-17. PIC Diagram



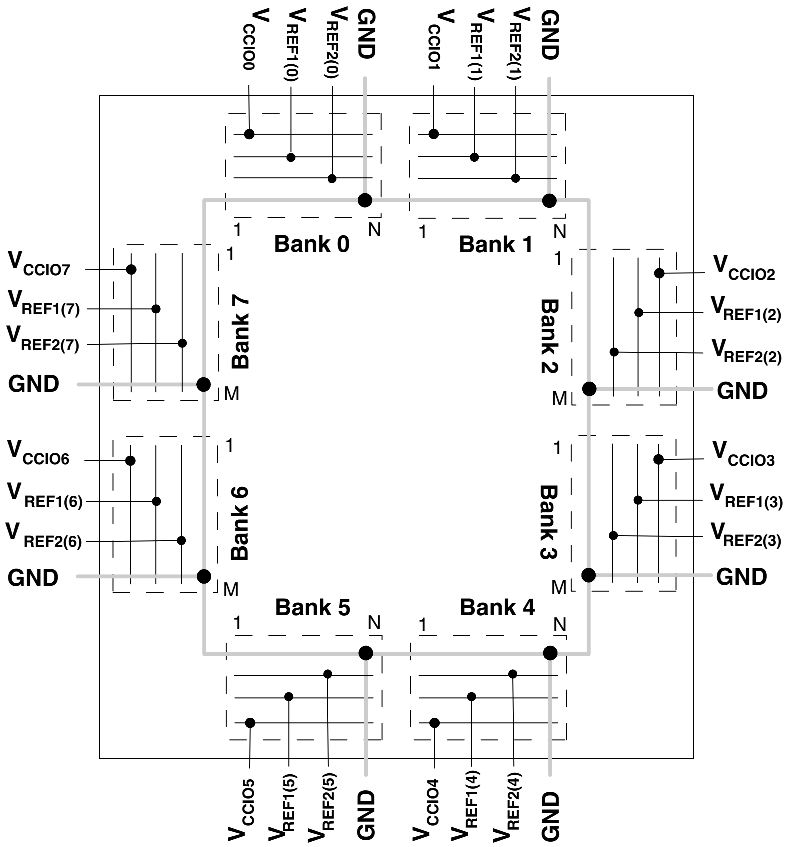
In the LatticeXP family, seven PIOs or four (3.5) PICs are grouped together to provide two LVDS differential pairs, one PIC pair and one single I/O, as shown in Figure 2-18.

Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as “T” and “C”). The PAD Labels “T” and “C” distinguish the two PIOs. Only the PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs.

One of every 14 PIOs (a group of 8 PICs) contains a delay element to facilitate the generation of DQS signals as shown in Figure 2-19. The DQS signal feeds the DQS bus which spans the set of 13 PIOs (8 PICs). The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. This interface is designed for memories that support one DQS strobe per eight bits of data.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table in this data sheet.

Figure 2-28. LatticeXP Banks



Note: N and M are the maximum number of I/Os per bank.

LatticeXP devices contain two types of sysIO buffer pairs.

1. **Top and Bottom sysIO Buffer Pair (Single-Ended Outputs Only)**
   The sysIO buffer pairs in the top and bottom banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

   The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

   Only the I/Os on the top and bottom banks have PCI clamps. Note that the PCI clamp is enabled after $V_{CC,}$ V_{CCAUX} and V_{CCIO} are at valid operating levels and the device has been configured.

2. **Left and Right sysIO Buffer Pair (Differential and Single-Ended Outputs)**
   The sysIO buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. The referenced input buffer can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

   Select I/Os in the left and right banks have LVDS differential output drivers. Refer to the Logic Signal Connections tables for more information.

Table 2-8. Supported Output Standards

Output Standard	Drive	V_{CCIO} (Nom.)
Single-ended Interfaces		
LVTTL	4mA, 8mA, 12mA, 16mA, 20mA	3.3
LVCMOS33	4mA, 8mA, 12mA 16mA, 20mA	3.3
LVCMOS25	4mA, 8mA, 12mA 16mA, 20mA	2.5
LVCMOS18	4mA, 8mA, 12mA 16mA	1.8
LVCMOS15	4mA, 8mA	1.5
LVCMOS12	2mA, 6mA	1.2
LVCMOS33, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVCMOS25, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVCMOS18, Open Drain	4mA, 8mA, 12mA 16mA	—
LVCMOS15, Open Drain	4mA, 8mA	—
LVCMOS12, Open Drain	2mA. 6mA	—
PCI33	N/A	3.3
HSTL18 Class I, II, III	N/A	1.8
HSTL15 Class I, III	N/A	1.5
SSTL3 Class I, II	N/A	3.3
SSTL2 Class I, II	N/A	2.5
SSTL18 Class I	N/A	1.8
Differential Interfaces		
Differential SSTL3, Class I, II	N/A	3.3
Differential SSTL2, Class I, II	N/A	2.5
Differential SSTL18, Class I	N/A	1.8
Differential HSTL18, Class I, II, III	N/A	1.8
Differential HSTL15, Class I, III	N/A	1.5
LVDS	N/A	2.5
BLVDS[1]	N/A	2.5
LVPECL[1]	N/A	3.3

1. Emulated with external resistors.

Hot Socketing

The LatticeXP devices have been carefully designed to ensure predictable behavior during power-up and power-down. Power supplies can be sequenced in any order. During power up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled to within specified limits, which allows easy integration with the rest of the system. These capabilities make the LatticeXP ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The LatticeXP “C” devices (V_{CC} = 1.8/2.5/3.3V) have a sleep mode that allows standby current to be reduced by up to three orders of magnitude during periods of system inactivity. Entry and exit to Sleep Mode is controlled by the SLEEPN pin.

During Sleep Mode, the FPGA logic is non-operational, registers and EBR contents are not maintained and I/Os are tri-stated. Do not enter Sleep Mode during device programming or configuration operation. In Sleep Mode, power supplies can be maintained in their normal operating range, eliminating the need for external switching of power supplies. Table 2-9 compares the characteristics of Normal, Off and Sleep Modes.

Table 2-9. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static Icc	Typical <100mA	0	Typical <100uA
I/O Leakage	<10µA	<1mA	<10µA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	Off	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up typically in the order of 10µA along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to V_{CC} is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically the device enters Sleep Mode several hundred ns after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet show a detailed timing diagram.

Configuration and Testing

The following section describes the configuration and testing features of the LatticeXP family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeXP devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeXP devices contain two possible ports that can be used for device configuration and programming. The test access port (TAP), which supports serial configuration, and the sysCONFIG port that supports both byte-wide and serial configuration.

The non-volatile memory in the LatticeXP can be configured in three different modes:

- In sysCONFIG mode via the sysCONFIG port. Note this can also be done in background mode.
- In 1532 mode via the 1149.1 port.
- In background mode via the 1149.1 port. This allows the device to be operated while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- In 1532 mode via the 1149.1 port SRAM direct configuration.
- In sysCONFIG mode via the sysCONFIG port SRAM direct configuration.

Lattice Semiconductor Corporation

LatticeXP Family Data Sheet DC and Switching Characteristics

November 2007 — Data Sheet DS1001

Absolute Maximum Ratings[1, 2, 3, 4]

	XPE (1.2V)	XPC (1.8V/2.5V/3.3V)
Supply Voltage V_{CC}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCP}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCAUX}	-0.5 to 3.75V	-0.5 to 3.75V
Supply Voltage V_{CCJ}	-0.5 to 3.75V	-0.5 to 3.75V
Output Supply Voltage V_{CCIO}	-0.5 to 3.75V	-0.5 to 3.75V
I/O Tristate Voltage Applied[5]	-0.5 to 3.75V	-0.5 to 3.75V
Dedicated Input Voltage Applied [5]	-0.5 to 3.75V	-0.5 to 4.25V
Storage Temperature (Ambient)	-65 to 150°C	-65 to 150°C
Junction Temp. (Tj)	+125°C	+125°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions outside of those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. All chip grounds are connected together to a common package GND plane.
5. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions[3]

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCP}	Supply Voltage for PLL for 1.2V Devices	1.14	1.26	V
	Supply Voltage for PLL for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCAUX}[4]	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCIO}[1, 2]	I/O Driver Supply Voltage	1.14	3.465	V
V_{CCJ}[1]	Supply Voltage for IEEE 1149.1 Test Access Port	1.14	3.465	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	85	C
t_{JIND}	Junction Temperature, Industrial Operation	-40	100	C
$t_{JFLASHCOM}$	Junction Temperature, Flash Programming, Commercial	0	85	C
$t_{JFLASHIND}$	Junction Temperature, Flash Programming, Industrial	0	85	C

1. If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as V_{CCAUX}. For the XPE devices (1.2V V_{CC}), if V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC}.
2. See recommended voltages by I/O standard in subsequent table.
3. The system designer must ensure that the FPGA design stays within the specified junction temperature and package thermal capabilities of the device based on the expected operating frequency, activity factor and environment conditions of the system.
4. V_{CCAUX} ramp rate must not exceed 30mV/µs during power up when transitioning between 0V and 3.3V.

sysIO Recommended Operating Conditions

Standard	V_{CCIO}			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3	3.135	3.3	3.465	—	—	—
LVCMOS 2.5	2.375	2.5	2.625	—	—	—
LVCMOS 1.8	1.71	1.8	1.89	—	—	—
LVCMOS 1.5	1.425	1.5	1.575	—	—	—
LVCMOS 1.2	1.14	1.2	1.26	—	—	—
LVTTL	3.135	3.3	3.465	—	—	—
PCI33	3.135	3.3	3.465	—	—	—
SSTL18 Class I	1.71	1.8	1.89	0.833	0.9	0.969
SSTL2 Class I, II	2.375	2.5	2.625	1.15	1.25	1.35
SSTL3 Class I, II	3.135	3.3	3.465	1.3	1.5	1.7
HSTL15 Class I	1.425	1.5	1.575	0.68	0.75	0.9
HSTL15 Class III	1.425	1.5	1.575	—	0.9	—
HSTL 18 Class I, II	1.71	1.8	1.89	—	0.9	—
HSTL 18 Class III	1.71	1.8	1.89	—	1.08	—
LVDS	2.375	2.5	2.625	—	—	—
LVPECL[1]	3.135	3.3	3.465	—	—	—
BLVDS[1]	2.375	2.5	2.625	—	—	—

1. Inputs on chip. Outputs are implemented with the addition of external resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

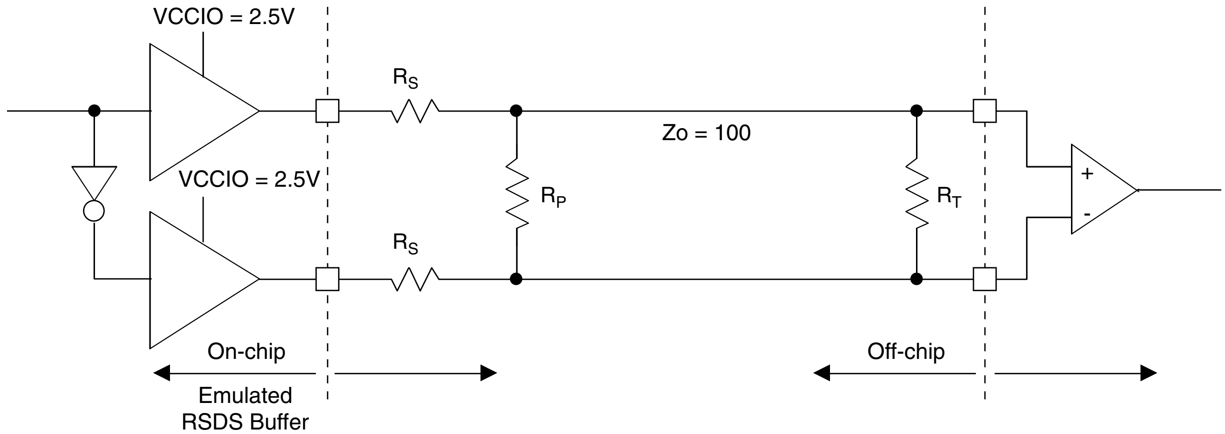


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	ohms
R_S	Driver series resistor	300	ohms
R_P	Driver parallel resistor	121	ohms
R_T	Receiver termination	100	ohms
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	ohms
I_{DC}	DC output current	3.66	mA

Typical Building Block Function Performance[1]

Pin-to-Pin Performance (LVCMOS25 12 mA Drive)

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	6.1	ns
32-bit decoder	7.3	ns
64-bit decoder	8.2	ns
4:1 MUX	4.9	ns
8:1 MUX	5.3	ns
16:1 MUX	5.7	ns
32:1 MUX	6.3	ns

Register to Register Performance

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	351	MHz
32-bit decoder	248	MHz
64-bit decoder	237	MHz
4:1 MUX	590	MHz
8:1 MUX	523	MHz
16:1 MUX	434	MHz
32:1 MUX	355	MHz
8-bit adder	343	MHz
16-bit adder	292	MHz
64-bit adder	130	MHz
16-bit counter	388	MHz
32-bit counter	295	MHz
64-bit counter	200	MHz
64-bit accumulator	164	MHz
Embedded Memory Functions		
Single Port RAM 256x36 bits	254	MHz
True-Dual Port RAM 512x18 bits	254	MHz
Distributed Memory Functions		
16x2 SP RAM	434	MHz
64x2 SP RAM	332	MHz
128x4 SP RAM	235	MHz
32x2 PDP RAM	322	MHz
64x4 PDP RAM	291	MHz

1. These timing numbers were generated using the ispLEVER design tool. Exact performance may vary with design and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

Timing v.F0.11

Signal Descriptions (Cont.)

Signal Name	I/O	Descriptions
Test and Programming (Dedicated pins. Pull-up is enabled on input pins during configuration.)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin -Test Data out pin used to shift data out of device using 1149.1.
V_{CCJ}	—	V_{CCJ} - The power supply pin for JTAG Test Access Port.
Configuration Pads (used during sysCONFIG)		
CFG[1:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN. During configuration, a pull-up is enabled.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled. If CFG1 and CFG0 are high (SDM) then this pin is pulled low.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.
BUSY	I/O	Generally not used. After configuration it is a user-programmable I/O pin.
CSN	I	sysCONFIG chip select (Active low). During configuration, a pull-up is enabled. After configuration it is user a programmable I/O pin.
CS1N	I	sysCONFIG chip select (Active Low). During configuration, a pull-up is enabled. After configuration it is user programmable I/O pin
WRITEN	I	Write Data on Parallel port (Active low). After configuration it is a user programmable I/O pin
D[7:0]	I/O	sysCONFIG Port Data I/O. After configuration these are user programmable I/O pins.
DOUT, CSON	O	Output for serial configuration data (rising edge of CCLK) when using sysCONFIG port. After configuration, it is a user-programmable I/O pin.
DI	I	Input for serial configuration data (clocked with CCLK) when using sysCONFIG port. During configuration, a pull-up is enabled. After configuration it is a user-programmable I/O pin.
SLEEPN[2]	I	Sleep Mode pin - Active low sleep pin.þ When this pin is held high, the device operates normally.þ When driven low, the device moves into Sleep Mode after a specified time.This pin has a weak internal pull-up, but when not used an external pull-up to V_{CC} is recommended.
TOE[3]	I	Test Output Enable tri-states all I/O pins when driven low. This pin has a weak internal pull-up, but when not used an external pull-up to V_{CC} is recommended.

1. Applies toþ LFXP10, LFXP15 and LFXP20 only.
2. Applies to LFXP “C” devices only.
3. Applies to LFXP “E” devices only.

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
C2	PROGRAMN	7	-	-	PROGRAMN	7	-	-
C1	CCLK	7	-	-	CCLK	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
D2	PL3A	7	T	LUM0_PLLT_FB_A	PL3A	7	T	LUM0_PLLT_FB_A
D3	PL3B	7	C	LUM0_PLLC_FB_A	PL3B	7	C	LUM0_PLLC_FB_A
D1	PL2A	7	T[3]	-	PL5A	7	-	-
E2	PL5A	7	-	VREF1_7	PL6B	7	-	VREF1_7
-	GNDIO7	7	-	-	GNDIO7	7	-	-
E1	PL7A	7	T[3]	DQS	PL7A	7	T[3]	DQS
F1	PL7B	7	C[3]	-	PL7B	7	C[3]	-
E3	PL12A	7	T	-	PL8A	7	T	-
F4	PL12B	7	C	-	PL8B	7	C	-
F3	PL4A	7	T[3]	-	PL9A	7	T[3]	-
F2	PL4B	7	C[3]	-	PL9B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
G1	PL2B	7	C[3]	-	PL11B	7	-	-
G3	PL8A	7	T	LUM0_PLLT_IN_A	PL12A	7	T	LUM0_PLLT_IN_A
G2	PL8B	7	C	LUM0_PLLC_IN_A	PL12B	7	C	LUM0_PLLC_IN_A
H1	PL9A	7	T[3]	-	PL13A	7	T[3]	-
H2	PL9B	7	C[3]	-	PL13B	7	C[3]	-
G4	PL6B	7	-	VREF2_7	PL14A	7	-	VREF2_7
G5	PL14A	7	-	-	PL15B	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
J1	PL11A	7	T[3]	-	PL16A	7	T[3]	DQS
J2	PL11B	7	C[3]	-	PL16B	7	C[3]	-
H3	PL13A	7	T[3]	-	PL18A	7	T[3]	-
J3	PL13B	7	C[3]	-	PL18B	7	C[3]	-
H4	VCCP0	-	-	-	VCCP0	-	-	-
H5	GNDP0	-	-	-	GNDP0	-	-	-
K1	PL17A	6	T	PCLKT6_0	PL20A	6	T	PCLKT6_0
K2	PL17B	6	C	PCLKC6_0	PL20B	6	C	PCLKC6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-
J4	PL15B	6	-	-	PL22A	6	-	-
J5	PL22A	6	-	VREF1_6	PL23B	6	-	VREF1_6
L1	PL16A	6	T[3]	-	PL24A	6	T[3]	DQS
L2	PL16B	6	C[3]	-	PL24B	6	C[3]	-
M1	PL18A	6	T[3]	-	PL25A	6	T	LLM0_PLLT_IN_A
M2	PL18B	6	C[3]	-	PL25B	6	C	LLM0_PLLC_IN_A
K3	PL19A	6	T[3]	-	PL26A	6	T[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
L3	PL19B	6	C[3]	-	PL26B	6	C[3]	-
L4	PL21A	6	T[3]	-	PL28A	6	-	-

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP6				LFXP10			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
E16	TDO	-	-	-	TDO	-	-	-
D16	VCCJ	-	-	-	VCCJ	-	-	-
D14	TDI	-	-	-	TDI	-	-	-
C14	TMS	-	-	-	TMS	-	-	-
B14	TCK	-	-	-	TCK	-	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
A15	PT31B	1	C	-	PT35B	1	C	-
B15	PT31A	1	T	-	PT35A	1	T	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
D12	PT28A	1	-	VREF1_1	PT34B	1	C	VREF1_1
C11	PT30A	1	T	DQS	PT34A	1	T	DQS
A14	PT29B	1	-	-	PT33B	1	-	-
B13	PT30B	1	C	-	PT32A	1	-	-
F12	PT27B	1	C	-	PT31B	1	C	-
E11	PT27A	1	T	-	PT31A	1	T	-
A13	PT26B	1	C	-	PT30B	1	C	-
C13	PT26A	1	T	D0	PT30A	1	T	D0
-	GNDIO1	1	-	-	GNDIO1	1	-	-
C10	PT25B	1	C	D1	PT29B	1	C	D1
E10	PT25A	1	T	VREF2_1	PT29A	1	T	VREF2_1
A12	PT24B	1	C	-	PT28B	1	C	-
B12	PT24A	1	T	D2	PT28A	1	T	D2
C12	PT23B	1	C	D3	PT27B	1	C	D3
A11	PT23A	1	T	-	PT27A	1	T	-
B11	PT22B	1	C	-	PT26B	1	C	-
D11	PT22A	1	T	DQS	PT26A	1	T	DQS
-	GNDIO1	1	-	-	GNDIO1	1	-	-
B9	PT21B	1	-	-	PT25B	1	-	-
D9	PT20A	1	-	D4	PT24A	1	-	D4
A10	PT19B	1	C	-	PT23B	1	C	-
B10	PT19A	1	T	D5	PT23A	1	T	D5
D10	PT18B	1	C	D6	PT22B	1	C	D6
A9	PT18A	1	T	-	PT22A	1	T	-
C9	PT17B	1	C	D7	PT21B	1	C	D7
C8	PT17A	1	T	-	PT21A	1	T	-
E9	PT16B	0	C	BUSY	PT20B	0	C	BUSY
-	GNDIO0	0	-	-	GNDIO0	0	-	-
B8	PT16A	0	T	CS1N	PT20A	0	T	CS1N
A8	PT15B	0	C	PCLKC0_0	PT19B	0	C	PCLKC0_0
A7	PT15A	0	T	PCLKT0_0	PT19A	0	T	PCLKT0_0
B7	PT14B	0	C	-	PT18B	0	C	-
C7	PT14A	0	T	DQS	PT18A	0	T	DQS

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L4	PL32A	6	-	-	PL36A	6	-	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
K4	PL33A	6	T	-	PL37A	6	T	-
K5	PL33B	6	C	-	PL37B	6	C	-
N1	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
N2	PL36B	6	-	-	PL40B	6	-	-
P1	PL37A	6	T[3]	DQS	PL41A	6	T[3]	DQS
P2	PL37B	6	C[3]	-	PL41B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
L5	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
M6	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
M3	PL39A	6	T[3]	-	PL43A	6	T[3]	-
N3	PL39B	6	C[3]	-	PL43B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
P4	SLEEPN[1]/TOE[2]	-	-	-	SLEEPN[1]/TOE[2]	-	-	-
P3	INITN	5	-	-	INITN	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R4	PB11A	5	T	-	PB15A	5	T	-
N5	PB11B	5	C	-	PB15B	5	C	-
P5	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R1	PB12B	5	C	-	PB16B	5	C	-
N6	PB13A	5	-	-	PB17A	5	-	-
M7	PB14B	5	-	-	PB18B	5	-	-
R2	PB15A	5	T	DQS	PB19A	5	T	DQS
T2	PB15B	5	C	-	PB19B	5	C	-
R3	PB16A	5	T	-	PB20A	5	T	-
T3	PB16B	5	C	-	PB20B	5	C	-
T4	PB17A	5	T	-	PB21A	5	T	-
R5	PB17B	5	C	VREF2_5	PB21B	5	C	VREF2_5
N7	PB18A	5	T	-	PB22A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
M8	PB18B	5	C	-	PB22B	5	C	-
T5	PB19A	5	T	-	PB23A	5	T	-
P6	PB19B	5	C	-	PB23B	5	C	-
T6	PB20A	5	T	-	PB24A	5	T	-
R6	PB20B	5	C	-	PB24B	5	C	-
P7	PB21A	5	-	-	PB25A	5	-	-
N8	PB22B	5	-	-	PB26B	5	-	-
R7	PB23A	5	T	DQS	PB27A	5	T	DQS

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
T7	PB23B	5	C	-	PB27B	5	C	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
P8	PB24A	5	T	-	PB28A	5	T	-
T8	PB24B	5	C	-	PB28B	5	C	-
R8	PB25A	5	T	-	PB29A	5	T	-
T9	PB25B	5	C	-	PB29B	5	C	-
R9	PB26A	4	T	-	PB30A	4	T	-
P9	PB26B	4	C	-	PB30B	4	C	-
T10	PB27A	4	T	PCLKT4_0	PB31A	4	T	PCLKT4_0
T11	PB27B	4	C	PCLKC4_0	PB31B	4	C	PCLKC4_0
-	GNDIO4	4	-	-	GNDIO4	4	-	-
R10	PB28A	4	T	-	PB32A	4	T	-
P10	PB28B	4	C	-	PB32B	4	C	-
N9	PB29A	4	-	-	PB33A	4	-	-
M9	PB30B	4	-	-	PB34B	4	-	-
R12	PB31A	4	T	DQS	PB35A	4	T	DQS
T12	PB31B	4	C	VREF1_4	PB35B	4	C	VREF1_4
P13	PB32A	4	T	-	PB36A	4	T	-
R13	PB32B	4	C	-	PB36B	4	C	-
M11	PB33A	4	T	-	PB37A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
N11	PB33B	4	C	-	PB37B	4	C	-
N10	PB34A	4	T	-	PB38A	4	T	-
M10	PB34B	4	C	-	PB38B	4	C	-
T13	PB35A	4	T	-	PB39A	4	T	-
P14	PB35B	4	C	-	PB39B	4	C	-
R11	PB36A	4	T	VREF2_4	PB40A	4	T	VREF2_4
P12	PB36B	4	C	-	PB40B	4	C	-
T14	PB37A	4	-	-	PB41A	4	-	-
R14	PB38B	4	-	-	PB42B	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
P11	PB39A	4	T	DQS	PB43A	4	T	DQS
N12	PB39B	4	C	-	PB43B	4	C	-
T15	PB40A	4	T	-	PB44A	4	T	-
R15	PB40B	4	C	-	PB44B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
P15	PR38B	3	C	RLM0_PLLC_FB_A	PR42B	3	C	RLM0_PLLC_FB_A
N15	PR38A	3	T	RLM0_PLLT_FB_A	PR42A	3	T	RLM0_PLLT_FB_A

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
P16	PR37B	3	C^3	-	PR41B	3	C^3	-
R16	PR37A	3	T^3	DQS	PR41A	3	T^3	DQS
M15	PR36B	3	-	-	PR40B	3	-	-
N14	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
M14	PR33B	3	C	-	PR37B	3	C	-
L13	PR33A	3	T	-	PR37A	3	T	-
L15	PR32B	3	C^3	-	PR36B	3	C^3	-
L14	PR32A	3	T^3	-	PR36A	3	T^3	-
L12	PR30A	3	-	-	PR34A	3	-	-
M16	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
N16	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-
K14	PR28B	3	C^3	-	PR32B	3	C^3	-
K15	PR28A	3	T^3	DQS	PR32A	3	T^3	DQS
K12	PR27B	3	-	-	PR31B	3	-	-
K13	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
L16	PR25B	3	C^3	-	PR29B	3	C^3	-
K16	PR25A	3	T^3	-	PR29A	3	T^3	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
J15	PR23B	3	C^3	-	PR27B	3	C^3	-
J14	PR23A	3	T^3	-	PR27A	3	T^3	-
J13	GNDP1	-	-	-	GNDP1	-	-	-
J12	VCCP1	-	-	-	VCCP1	-	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J16	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
H16	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0
H13	PR20B	2	C^3	-	PR20B	2	C^3	-
H12	PR20A	2	T^3	DQS	PR20A	2	T^3	DQS
H15	PR19B	2	-	-	PR19B	2	-	-
H14	PR18A	2	-	VREF1_2	PR18A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G15	PR17B	2	C^3	-	PR17B	2	C^3	-
G14	PR17A	2	T^3	-	PR17A	2	T^3	-
G16	PR16B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A
F16	PR16A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A
G13	PR15B	2	-	-	PR15B	2	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G12	PR12B	2	C	-	PR12B	2	C	-
F13	PR12A	2	T	-	PR12A	2	T	-
B16	PR11B	2	C^3	-	PR11B	2	C^3	-
C16	PR11A	2	T^3	DQS	PR11A	2	T^3	DQS

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
G7	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
T16	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
T7	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
G10	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G11	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G8	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G9	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
H8	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G12	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G13	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G14	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G15	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
H15	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
H16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
J16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
K16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
L16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
M16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
N16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
P16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
R16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
R15	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T12	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T13	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T14	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T15	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
R8	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T10	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T11	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T8	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T9	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
M7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
N7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
P7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
R7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
H7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
J7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
K7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
L7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
J15	GND	-	-	-	GND	-	-	-
J8	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-
K10	GND	-	-	-	GND	-	-	-
K11	GND	-	-	-	GND	-	-	-
K12	GND	-	-	-	GND	-	-	-
K13	GND	-	-	-	GND	-	-	-
K14	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-
L10	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-
L12	GND	-	-	-	GND	-	-	-
L13	GND	-	-	-	GND	-	-	-
L14	GND	-	-	-	GND	-	-	-
L9	GND	-	-	-	GND	-	-	-
M10	GND	-	-	-	GND	-	-	-
M11	GND	-	-	-	GND	-	-	-
M12	GND	-	-	-	GND	-	-	-
M13	GND	-	-	-	GND	-	-	-
M14	GND	-	-	-	GND	-	-	-
M9	GND	-	-	-	GND	-	-	-
N10	GND	-	-	-	GND	-	-	-
N11	GND	-	-	-	GND	-	-	-
N12	GND	-	-	-	GND	-	-	-
N13	GND	-	-	-	GND	-	-	-
N14	GND	-	-	-	GND	-	-	-
N9	GND	-	-	-	GND	-	-	-
P10	GND	-	-	-	GND	-	-	-
P11	GND	-	-	-	GND	-	-	-
P12	GND	-	-	-	GND	-	-	-
P13	GND	-	-	-	GND	-	-	-
P14	GND	-	-	-	GND	-	-	-
P15	GND	-	-	-	GND	-	-	-
P8	GND	-	-	-	GND	-	-	-
P9	GND	-	-	-	GND	-	-	-
R14	GND	-	-	-	GND	-	-	-
R9	GND	-	-	-	GND	-	-	-
F10	VCC	-	-	-	VCC	-	-	-
F13	VCC	-	-	-	VCC	-	-	-
G10	VCC	-	-	-	VCC	-	-	-
G13	VCC	-	-	-	VCC	-	-	-
G14	VCC	-	-	-	VCC	-	-	-

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3F256C	188	1.2V	-3	fpBGA	256	COM	5.8K
LFXP6E-4F256C	188	1.2V	-4	fpBGA	256	COM	5.8K
LFXP6E-5F256C	188	1.2V	-5	fpBGA	256	COM	5.8K
LFXP6E-3Q208C	142	1.2V	-3	PQFP	208	COM	5.8K
LFXP6E-4Q208C	142	1.2V	-4	PQFP	208	COM	5.8K
LFXP6E-5Q208C	142	1.2V	-5	PQFP	208	COM	5.8K
LFXP6E-3T144C	100	1.2V	-3	TQFP	144	COM	5.8K
LFXP6E-4T144C	100	1.2V	-4	TQFP	144	COM	5.8K
LFXP6E-5T144C	100	1.2V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3F388C	244	1.2V	-3	fpBGA	388	COM	9.7K
LFXP10E-4F388C	244	1.2V	-4	fpBGA	388	COM	9.7K
LFXP10E-5F388C	244	1.2V	-5	fpBGA	388	COM	9.7K
LFXP10E-3F256C	188	1.2V	-3	fpBGA	256	COM	9.7K
LFXP10E-4F256C	188	1.2V	-4	fpBGA	256	COM	9.7K
LFXP10E-5F256C	188	1.2V	-5	fpBGA	256	COM	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3F484C	300	1.2V	-3	fpBGA	484	COM	15.5K
LFXP15E-4F484C	300	1.2V	-4	fpBGA	484	COM	15.5K
LFXP15E-5F484C	300	1.2V	-5	fpBGA	484	COM	15.5K
LFXP15E-3F388C	268	1.2V	-3	fpBGA	388	COM	15.5K
LFXP15E-4F388C	268	1.2V	-4	fpBGA	388	COM	15.5K
LFXP15E-5F388C	268	1.2V	-5	fpBGA	388	COM	15.5K
LFXP15E-3F256C	188	1.2V	-3	fpBGA	256	COM	15.5K
LFXP15E-4F256C	188	1.2V	-4	fpBGA	256	COM	15.5K
LFXP15E-5F256C	188	1.2V	-5	fpBGA	256	COM	15.5K

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3F484I	300	1.8/2.5/3.3V	-3	fpBGA	484	IND	15.5K
LFXP15C-4F484I	300	1.8/2.5/3.3V	-4	fpBGA	484	IND	15.5K
LFXP15C-3F388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	15.5K
LFXP15C-4F388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	15.5K
LFXP15C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	15.5K
LFXP15C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3F484I	340	1.8/2.5/3.3V	-3	fpBGA	484	IND	19.7K
LFXP20C-4F484I	340	1.8/2.5/3.3V	-4	fpBGA	484	IND	19.7K
LFXP20C-3F388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	19.7K
LFXP20C-4F388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	19.7K
LFXP20C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	19.7K
LFXP20C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3Q208I	136	1.2V	-3	PQFP	208	IND	3.1K
LFXP3E-4Q208I	136	1.2V	-4	PQFP	208	IND	3.1K
LFXP3E-3T144I	100	1.2V	-3	TQFP	144	IND	3.1K
LFXP3E-4T144I	100	1.2V	-4	TQFP	144	IND	3.1K
LFXP3E-3T100I	62	1.2V	-3	TQFP	100	IND	3.1K
LFXP3E-4T100I	62	1.2V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3F256I	188	1.2V	-3	fpBGA	256	IND	5.8K
LFXP6E-4F256I	188	1.2V	-4	fpBGA	256	IND	5.8K
LFXP6E-3Q208I	142	1.2V	-3	PQFP	208	IND	5.8K
LFXP6E-4Q208I	142	1.2V	-4	PQFP	208	IND	5.8K
LFXP6E-3T144I	100	1.2V	-3	TQFP	144	IND	5.8K
LFXP6E-4T144I	100	1.2V	-4	TQFP	144	IND	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3F388I	244	1.2V	-3	fpBGA	388	IND	9.7K
LFXP10E-4F388I	244	1.2V	-4	fpBGA	388	IND	9.7K
LFXP10E-3F256I	188	1.2V	-3	fpBGA	256	IND	9.7K
LFXP10E-4F256I	188	1.2V	-4	fpBGA	256	IND	9.7K

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
April 2005	01.1	Architecture	EBR memory support section updated with clarification.
May 2005	01.2	Introduction	Added TransFR Reconfiguration to Features section.
		Architecture	Added TransFR section.
June 2005	01.3	Pinout Information	Added pinout information for LFXP3, LFXP6, LFXP15 and LFXP20.
July 2005	02.0	Introduction	Updated XP6, XP15 and XP20 EBR SRAM Bits and Block numbers.
		Architecture	Updated Per Quadrant Primary Clock Selection figure.
			Added Typical I/O Behavior During Power-up section.
			Updated Device Configuration section under Configuration and Testing.
		DC and Switching Characteristics	Clarified Hot Socketing Specification
			Updated Supply Current (Standby) Table
			Updated Initialization Supply Current Table
			Added Programming and Erase Flash Supply Current table
			Added LVDS Emulation section. Updated LVDS25E Output Termination Example figure and LVDS25E DC Conditions table.
			Updated Differential LVPECL diagram and LVPECL DC Conditions table.
			Deleted 5V Tolerant Input Buffer section. Updated RSDS figure and RSDS DC Conditions table.
			Updated sysCONFIG Port Timing Specifications
			Updated JTAG Port Timing Specifications. Added Flash Download Time table.
		Pinout Information	Updated Signal Descriptions table.
			Updated Logic Signal Connections Dual Function column.
		Ordering Information	Added lead-free ordering part numbers.
July 2005	02.1	DC and Switching Characteristics	Clarification of Flash Programming Junction Temperature
August 2005	02.2	Introduction	Added Sleep Mode feature.
		Architecture	Added Sleep Mode section.
		DC and Switching Characteristics	Added Sleep Mode Supply Current Table
			Added Sleep Mode Timing section
		Pinout Information	Added SLEEPN and TOE signal names, descriptions and footnotes.
			Added SLEEPN and TOE to pinout information and footnotes.
			Added footnote 3 to Logic Signal Connections tables for clarification on emulated LVDS output.
September 2005	03.0	Architecture	Added clarification of PCI clamp.
			Added clarification to SLEEPN Pin Characteristics section.
		DC and Switching Characteristics	DC Characteristics, added footnote 4 for clarification. Updated Supply Current (Sleep Mode), Supply Current (Standby), Initialization Supply Current, and Programming and Erase Flash Supply Current typical numbers.